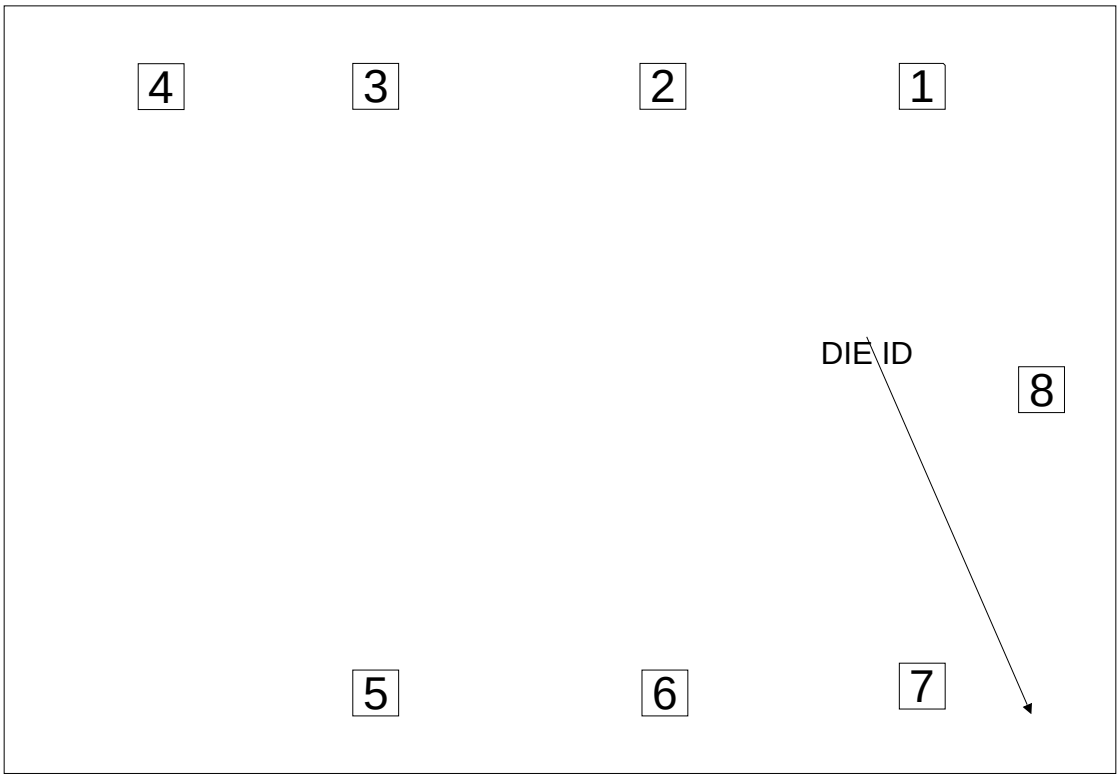
LMP2012 MDR MCD3090A
Dual, High Precision, Rail-to-Rail Output Operational Amplifier

NOV 16, 2009

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMV2012A	Bond Pad Opening Size (min)	88.00µm x 88.00µm
Die Step	A	Bond Pad Metalization	AL1.0%SI0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	2133.60µm x 1473.20µm 84.0mils x 58.0mils	Back Side Connection	Floating or GND
Thickness	304.8µm Nominal		
Min Pitch	493.92µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(A-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
	1	695	582	88	x	88
	2	198	582	88	x	88
	3	-354	582	88	x	88
	4	-766	582	88	x	88
	5	-354	-582	88	x	88
	6	201	-582	88	x	88
	7	695	-569	88	x	88
	8	924	0	88	x	88

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Notes

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